



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Miwa KOZAWA et al.**

Group Art Unit: **1752**

Application Number: **10/629,806**

Examiner: **Sin J. Lee**

Filed: **July 30, 2003**

Confirmation No.: **9494**

For: **RESIST PATTERN THICKENING MATERIAL, PROCESS FOR
FORMING RESIST PATTERN, AND PROCESS FOR
MANUFACTURING SEMICONDUCTOR DEVICE**

Attorney Docket Number: **030923**
Customer Number: **38834**

AMENDMENT AFTER FINAL

MAILSTOP: AF
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

April 11, 2006

Sir:

In response to the Office Action dated December 13, 2005, the response due date extended to April 13, 2006 by a 1-month Extension of Time, please amend the above-identified application as follows:

Please Enter
S.J.L.
4-21
-2006

Amendments to the Claims begin at page 2 of this paper.

Remarks begin on page 8 of this paper.

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